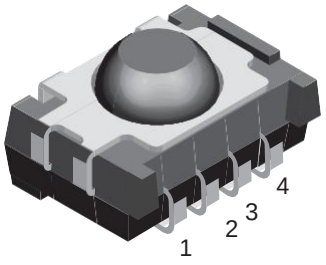
IR Receiver Modules for Remote Control Systems



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FEATURES

- Improved immunity against HF and RF noise
- Low supply current
- Photo detector and preamplifier in one package
- Internal filter for PCM frequency
- Supply voltage: 2.5 V to 5.5 V
- Improved immunity against optical noise
- Insensitive to supply voltage ripple and noise
- Taping available for top view and side view assembly

Pb-free

e3

RoHS COMPLIANT

HALOGEN FREE

GREEN (5-2008)

MECHANICAL DATA

Pinning

1 = GND, 2 = N.C., 3 = V_S, 4 = OUT

ORDERING CODE

Taping:

TSOP6...TT - top view taped

TSOP6...TR - side view taped

DESCRIPTION

The TSOP6... series are miniaturized SMD IR receiver modules for infrared remote control systems. A PIN diode and a preamplifier are assembled on a leadframe, the epoxy package contains an IR filter.

The demodulated output signal can be directly connected to a microprocessor for decoding.

The TSOP64.. series devices are optimized to suppress almost all spurious pulses from Wi-Fi and CFL sources. They may suppress some data signals if continuously transmitted.

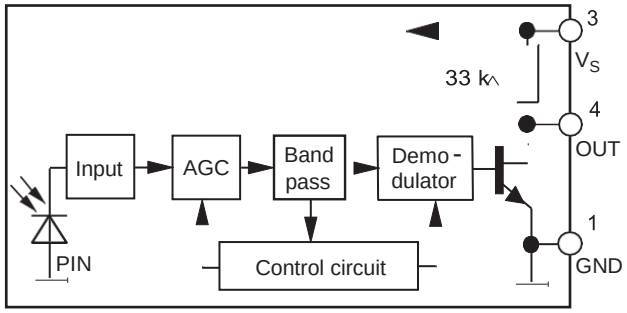
The TSOP62.. series devices are provided primarily for compatibility with old AGC2 designs. New designs should prefer the TSOP64.. series containing the newer AGC4.

These components have not been qualified according to automotive specifications.

PARTS TABLE

AGC		LEGACY, FOR LONG BURST REMOTE CONTROLS (AGC2)	RECOMMENDED FOR LONG BURST CODES (AGC4)
Carrier frequency	30 kHz	TSOP6230	TSOP6430
	33 kHz	TSOP6233	TSOP6433
	36 kHz	TSOP6236	TSOP6436 (1)(2)(3)
	38 kHz	TSOP6238	TSOP6438 (4)(5)
	40 kHz	TSOP6240	TSOP6440
	56 kHz	TSOP6256	TSOP6456 (6)(7)
Package		Panhead	
Pinning		1 = GND, 2 = N.C., 3 = V_S, 4 = OUT	
Dimensions (mm)		7.5 W x 5.3 H x 4.0 D	
Mounting		SMD	
Application		Remote control	
Best choice for		(1) RC-5 (2) RC-6 (3) Panasonic (4) NEC (5) Sharp (6) r-step (7) Thomson RCA	

BLOCK DIAGRAM



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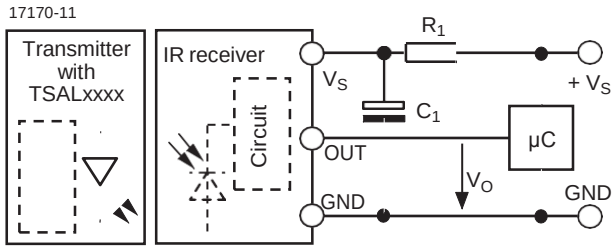
APPLICATION CIRCUIT



R_1 and C_1 recommended to reduce supply ripple for V_S < 2.8 V

ABSOLUTE MAXIMUM RATINGS				
PARAMETER	**TEST CONDITION**	**SYMBOL**	**VALUE**	**UNIT**
Supply voltage		V_S	-0.3 to +6	V
Supply current		I_S	5	mA
Output voltage		V_O	-0.3 to (V_S + 0.3)	V
Output current		I_O	5	mA
Junction temperature		T_j	100	°C
Storage temperature range		T_{stg}	-25 to +85	°C
Operating temperature range		T_{amb}	-25 to +85	°C
Power consumption	$T_{amb} \leq 85$ °C	P_{tot}	10	mW

Note

- Stresses beyond those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect the device reliability

ELECTRICAL AND OPTICAL CHARACTERISTICS (T_{amb} = 25 °C, unless otherwise specified)						
PARAMETER	**TEST CONDITION**	**SYMBOL**	**MIN.**	**TYP.**	**MAX.**	**UNIT**
Supply voltage		V_S	2.5	-	5.5	V
Supply current	V_S = 5 V, E_v = 0	I_{SD}	0.55	0.7	0.9	mA
	E_v = 40 klx, sunlight	I_{SH}	-	0.8	-	mA
Transmission distance	E_v = 0, IR diode TSAL6200, I_F = 250 mA, test signal see Fig. 1	d	-	40	-	m
Output voltage low	I_{OSL} = 0.5 mA, E_e = 0.7 mW/m², test signal see Fig. 1	V_{OSL}	-	-	100	mV
Minimum irradiance	Pulse width tolerance: t_{pi} - 5/f_o < t_{po} < t_{pi} + 6/f_o, test signal see Fig. 1	$E_{e\ min.}$	-	0.2	0.4	mW/m²
Maximum irradiance	t_{pi} - 5/f_o < t_{po} < t_{pi} + 6/f_o, test signal see Fig. 1	$E_{e\ max.}$	50	-	-	W/m²
Directivity	Angle of half transmission distance	$\varphi_{1/2}$	-	± 50	-	deg

TYPICAL CHARACTERISTICS (T_{amb} = 25 °C, unless otherwise specified)

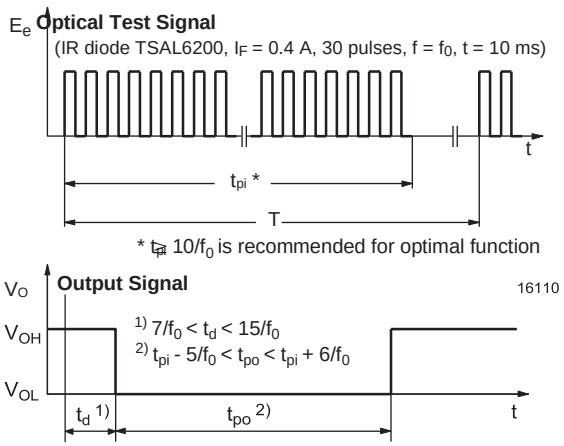


Fig. 1 - Output Active Low

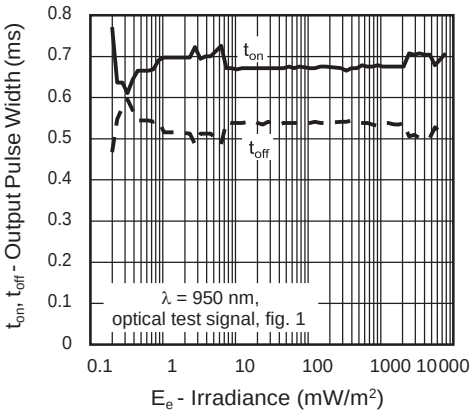


Fig. 4 - Output Pulse Diagram

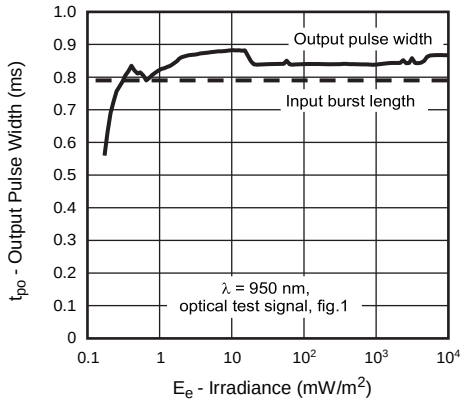


Fig. 2 - Pulse Length and Sensitivity in Dark Ambient

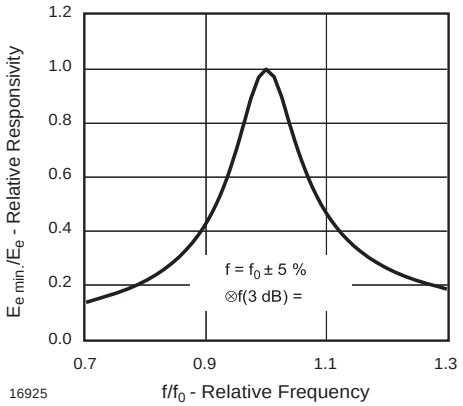


Fig. 5 - Frequency Dependence of Responsivity

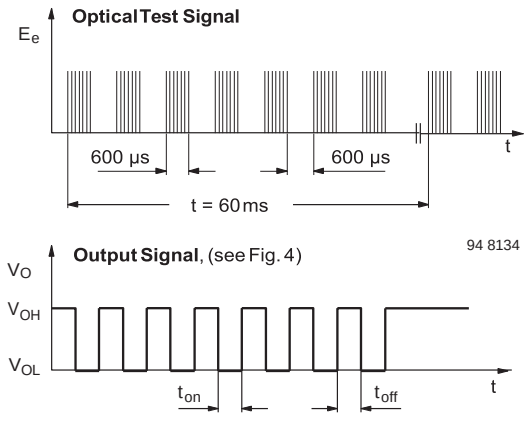


Fig. 3 - Output Function

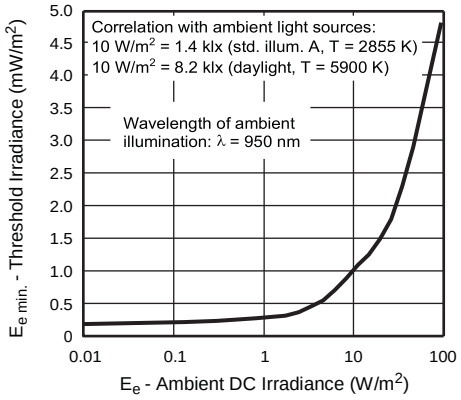


Fig. 6 - Sensitivity in Bright Ambient

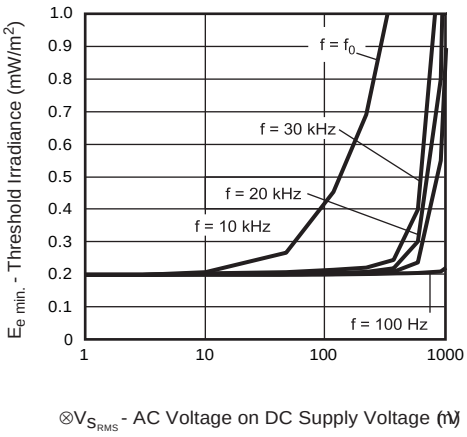


Fig. 7 - Sensitivity vs. Supply Voltage Disturbances

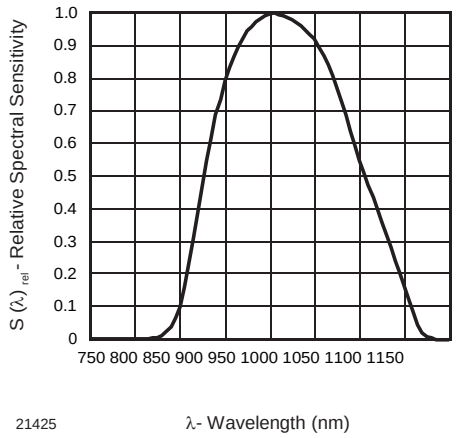


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Fig. 10 - Relative Spectral Sensitivity vs. Wavelength

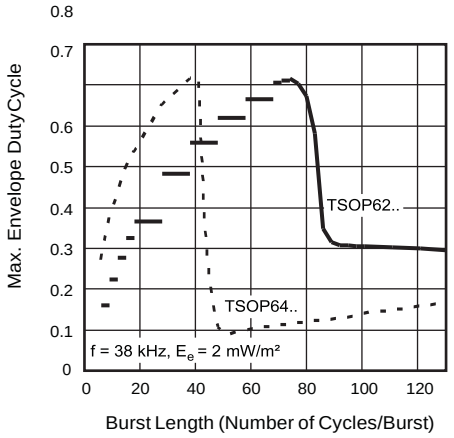

Fig. 8 - Max. Envelope Duty Cycle vs. Burst Length

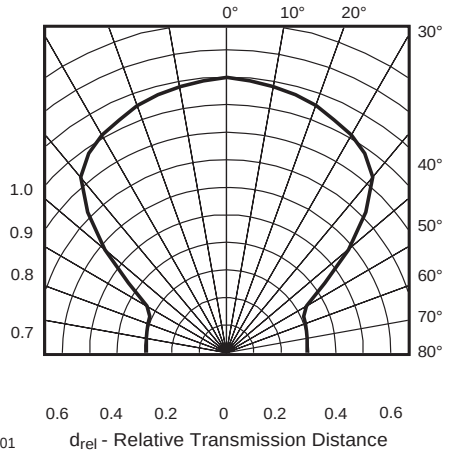

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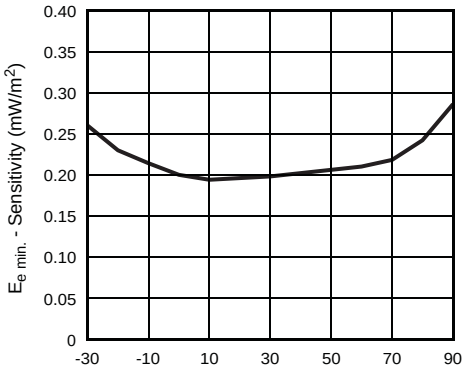
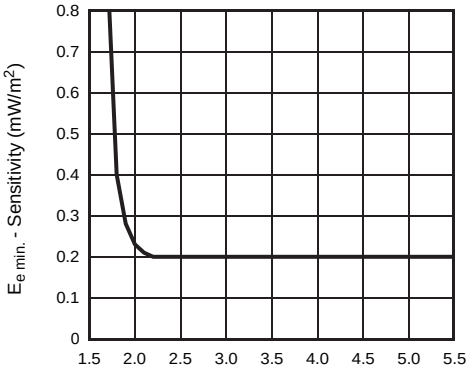
Fig. 11 - Horizontal Directivity





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This series is designed to suppress spurious output pulses due to noise or disturbance signals. The devices can distinguish data signals from noise due to differences in frequency, burst length, and envelope duty cycle. The data signal should be close to the device's band-pass center frequency (e.g. 38 kHz) and fulfill the conditions in the table below.

When a data signal is applied to the product in the presence of a disturbance, the sensitivity of the receiver is automatically reduced by the AGC to insure that no spurious pulses are present at the receiver's output.

Some examples which are suppressed are:

- DC light (e.g. from tungsten bulbs sunlight)
- Continuous signals at any frequency
- Strongly or weakly modulated noise from fluorescent lamps with electronic ballasts (see Fig. 13 or Fig. 14)
- 2.4 GHz and 5 GHz Wi-Fi

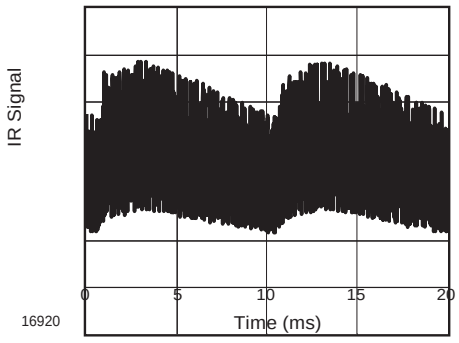


Fig. 13 - IR Disturbance from Fluorescent Lamp with Low Modulation

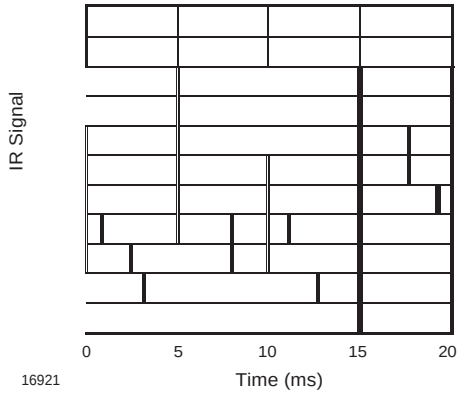


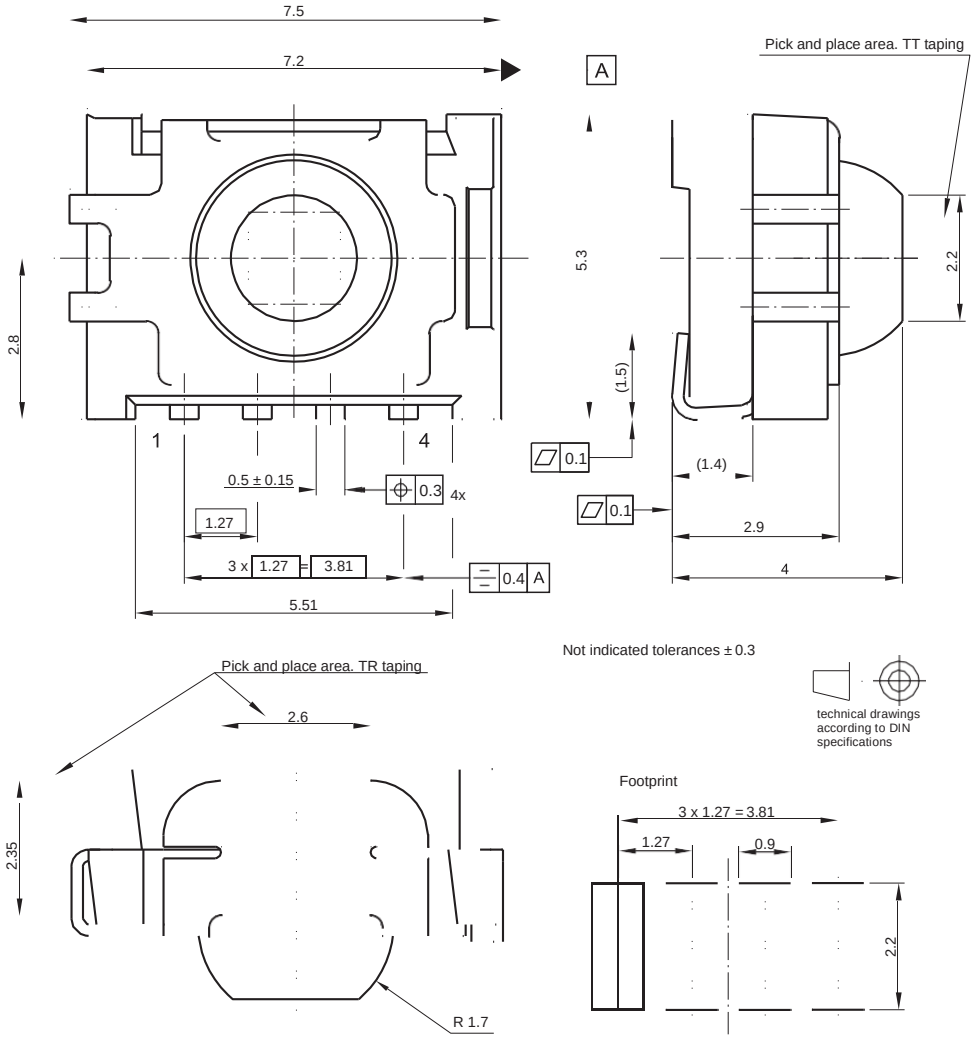
Fig. 14 - IR Disturbance from Fluorescent Lamp with High Modulation

	TSOP62..	TSOP64..
Minimum burst length	10 cycles/burst	10 cycles/burst
After each burst of length a minimum gap time is required of	10 to 70 cycles ≥ 12 cycles	10 to 35 cycles ≥ 12 cycles
For bursts greater than a minimum gap time in the data stream is needed of	70 cycles > 4 x burst length	35 cycles > 10 x burst length
Maximum number of continuous short bursts/second	800	1300
NEC code	Yes	Preferred
RC5 / RC6 code	Yes	Preferred
Thomson 56 kHz code	Yes	Preferred
Sharp code	Yes	Preferred
Suppression of interference from fluorescent lamps	Mild disturbance patterns are suppressed (example: signal pattern of Fig. 13)	Complex and critical disturbance patterns are suppressed (example: signal pattern of Fig. 14 or highly dimmed LCDs)

Note

- For data formats with short bursts please see the datasheet of TSOP61.., TSOP63.., TSOP65..

PACKAGE DIMENSIONS in millimeters



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Issue: 8; 02.09.09
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ASSEMBLY INSTRUCTIONS

Reflow Soldering

- Reflow soldering must be done within 72 h while stored under a max. temperature of 30 °C, 60 % RH after opening the dry pack envelope
- Set the furnace temperatures for pre-heating and heating in accordance with the reflow temperature profile as shown in the diagram. Exercise extreme care to keep the maximum temperature below 260 °C. The temperature shown in the profile means the temperature at the device surface. Since there is a temperature difference between the component and the circuit board, it should be verified that the temperature of the device is accurately being measured
- Handling after reflow should be done only after the work surface has been cooled off

Manual Soldering

- Use a soldering iron of 25 W or less. Adjust the temperature of the soldering iron below 300 °C
- Finish soldering within 3 s
- Handle products only after the temperature has cooled off